



QNHCHIP

QND160N03C

Product Specification

QND160N03C

30V N-Channel MOSFET



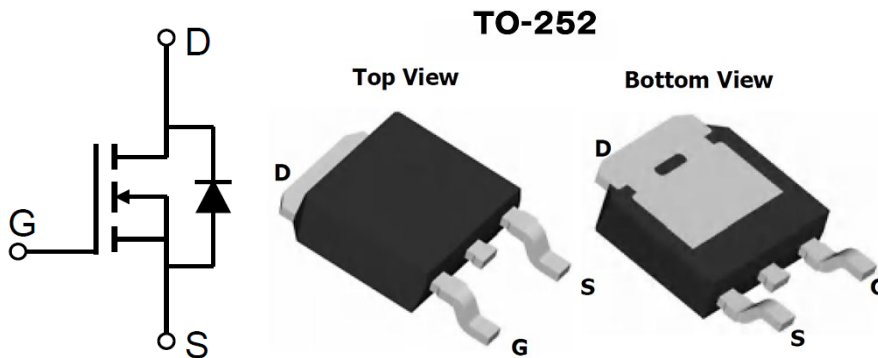
FEATURES

- 30V, 160A
 $R_{DS(ON)} < 3.5m\Omega @ V_{GS} = 10V$
 $R_{DS(ON)} < 4.5m\Omega @ V_{GS} = 4.5V$
- Advanced Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead Free

Applications

- Load Switch
- PWM Application
- Power Management

Pin Description



NO.	Symbol	Description
1	G	GATE
2	D	DRAIN
3	S	SOURCE



Absolute Maximum Ratings

(@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Value	Unit	
V_{DS}	Drain-to-Source Voltage	30	V	
V_{GS}	Gate-to-Source Voltage	± 20	V	
I_D	Continuous Drain Current ⁽¹⁾	$T_C = 25^\circ\text{C}$	160	A
		$T_C = 100^\circ\text{C}$	75	
I_{DM}	Pulsed Drain Current ⁽²⁾	385	A	
I_{AS}	Avalanche Current ⁽³⁾	25	A	
E_{AS}	Avalanche Energy ⁽³⁾	94	mJ	
P_D	Power Dissipation ⁽⁴⁾	$T_C = 25^\circ\text{C}$	74	W
		$T_C = 100^\circ\text{C}$	29	
T_J, T_{STG}	Junction & Storage Temperature Range	-55 to 150	$^\circ\text{C}$	



Electrical Characteristics

(T_J = 25°C unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
STATIC PARAMETERS						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	I _D = 1mA, V _{GS} = 0V	30			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 24V, V _{GS} = 0V			1.0	A
		T _J = 55°C			5.0	
Gate-Body Leakage Current	I _{GSS}	V _{DS} = 0V, V _{GS} = ±20V			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250uA	1.0	1.5	2.5	V
Static Drain-Source ON-Resistance	R _{DS(ON)}	V _{GS} = 10V, I _D = 20A		2.7	3.5	mΩ
		V _{GS} = 4.5V, I _D = 15A		4.2	5.5	mΩ
Forward Transconductance	g _{FS}	V _{DS} = 5V, I _D = 20A		128		S
Diode Forward Voltage	V _{SD}	I _S = 1A, V _{GS} = 0V		0.69	1.0	V
Diode Continuous Current	I _S	T _C =25°C			160	A
DYNAMIC PARAMETERS ⁽⁵⁾						
Input Capacitance	C _{iss}	V _{GS} =0V, V _{DS} =15V, f=1MHz		4221		pF
Output Capacitance	C _{oss}			420		pF
Reverse Transfer capacitance	C _{rss}			375		pF
Gate Resistance	R _g	V _{GS} = 0V, V _{DS} = 0V, f = 1MHz		21		
SWITCHING PARAMETERS ⁽⁵⁾						
Total Gate Charge (@V _{GS} =10V)	Q _g	V _{GS} = 0 to 10V V _{DS} = 15V, I _D = 20A		40		nC
Total Gate Charge (@V _{GS} =4.5V)	Q _g			18.8		nC
Gate Source Charge	Q _{gs}			5.3		nC
Gate Drain Charge	Q _{gd}			5.2		nC
Turn-On DelayTime	t _{D(on)}	V _{GS} = 10V, V _{DS} = 15V R _L =0.75 Ω , R _{GEN} =6 Ω		7.1		ns
Turn-On Rise Time	t _r			8.4		ns
Turn-Off DelayTime	t _{D(off)}			38		ns
Turn-Off Fall Time	t _f			22		ns
Body Diode Reverse Recovery Time	t _{rr}	I _F =20A, dI _F /dt=100A/us		48		ns
Body Diode Reverse Recovery Charge	Q _{rr}	I _F =20A, dI _F /dt=100A/us		45		nC
Thermal Performance						
Thermal Resistance, Junction-to-Ambient	R _{θJA}	38		45		°C/W
Thermal Resistance, Junction-to-Case	R _{θJC}	1.3		1.7		°C/W

Notes:

1. Computed continuous current assumes the condition of T_{J_Max} while the actual continuous current depends on the thermal & electro-mechanical application board design.
2. This single-pulse measurement was taken under T_{J_Max} = 150°C.
3. This single-pulse measurement was taken under the following condition [L = 300uH, V_{GS} = 10V, V_{DS} = 30V] while its value is limited by T_{J_Max} = 150°C.
4. The power dissipation P_D is based on T_{J_Max} = 150°C.
5. This value is guaranteed by design hence it is not included in the production test.



Test Circuit

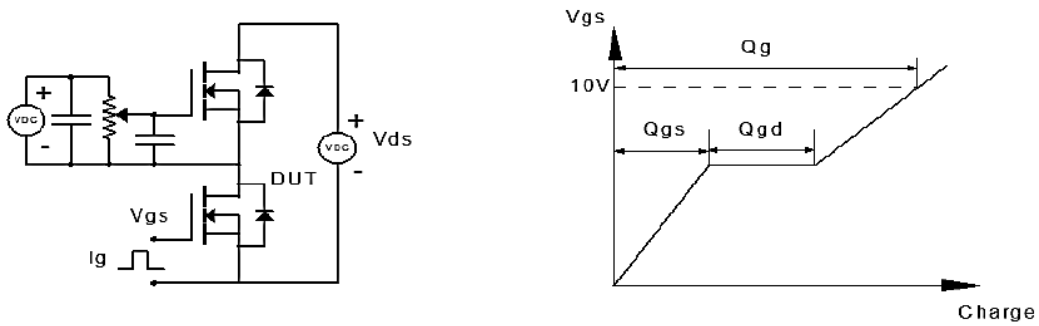


Figure 1: Gate Charge Test Circuit & Waveform

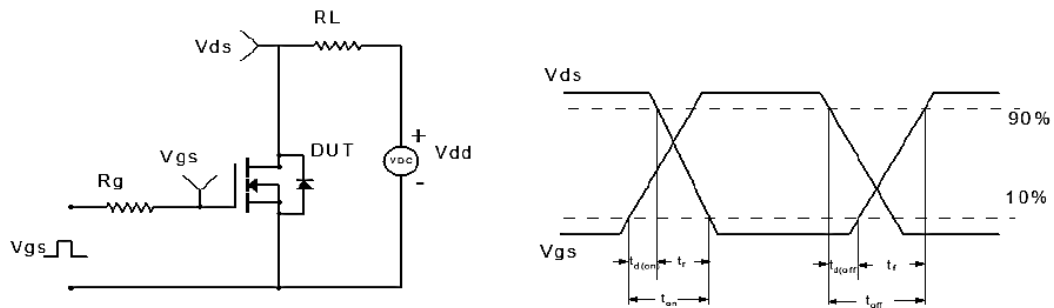


Figure 2: Resistive Switching Test Circuit & Waveform

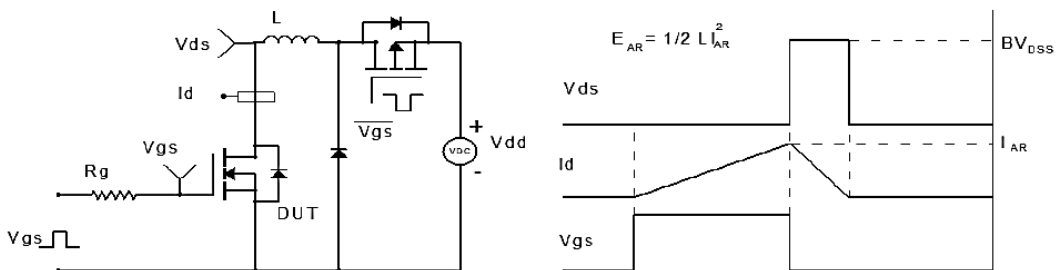


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

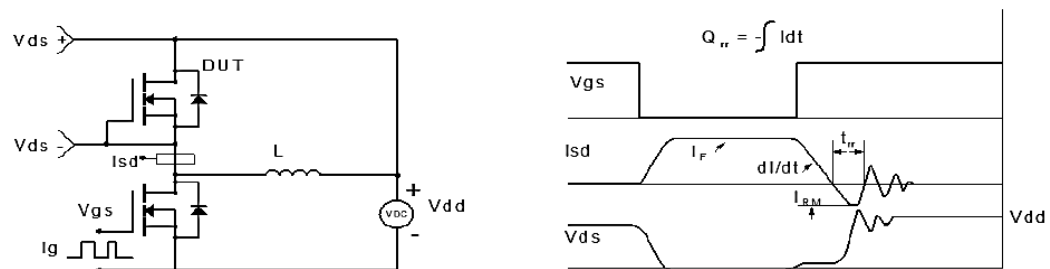
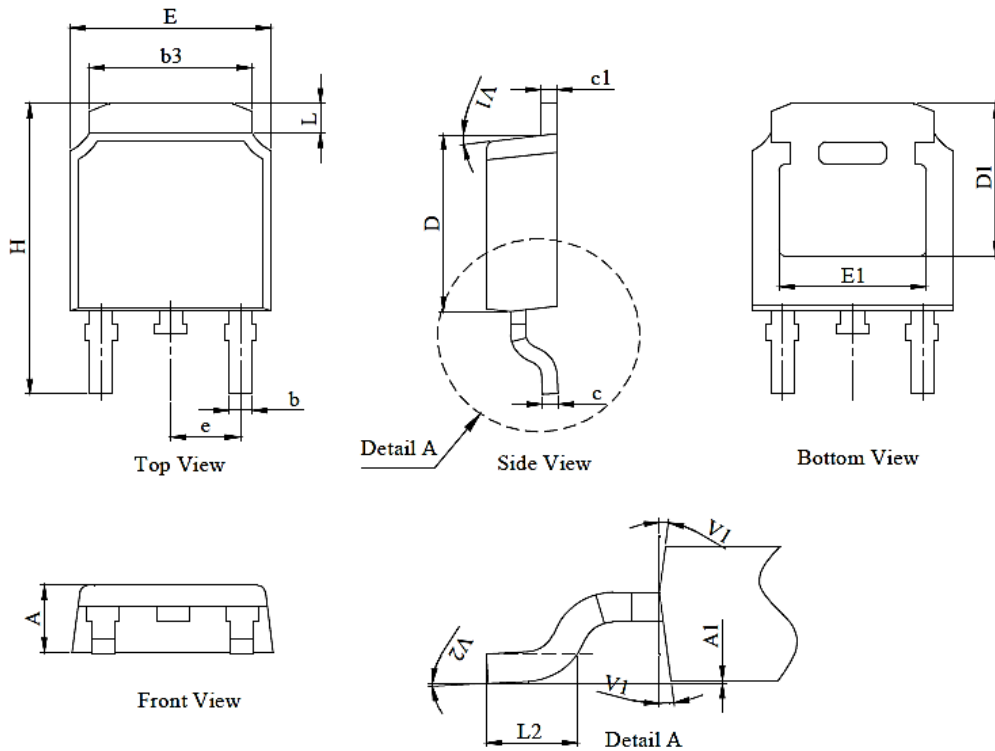


Figure 4: Diode Recovery Test Circuit & Waveform



TO-252-3L Package Information

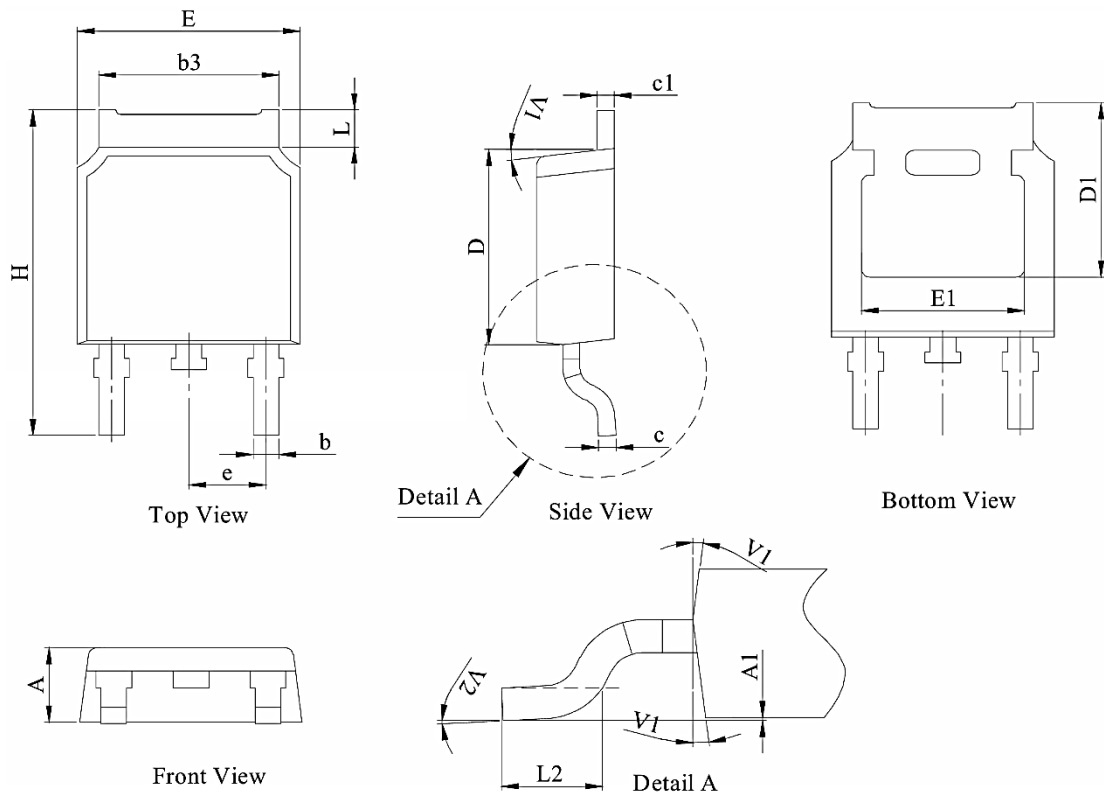
Package Outline Type-A



DIM	MILLIMETER		
	MIN.	NOM.	MAX.
A	2.18	2.30	2.39
A1	0	--	0.13
b	0.64	0.76	0.89
c	0.40	0.50	0.61
c1	0.46	0.50	0.58
D	5.97	6.10	6.23
D1	5.05	--	--
E	6.35	6.60	6.73
E1	4.32	--	--
b3	5.21	5.38	5.55
e	2.29 BSC		
H	9.40	10.00	10.40
L	0.89	--	1.27
L2	1.40	--	1.78
V1	7° REF		
V2	0°	--	6°



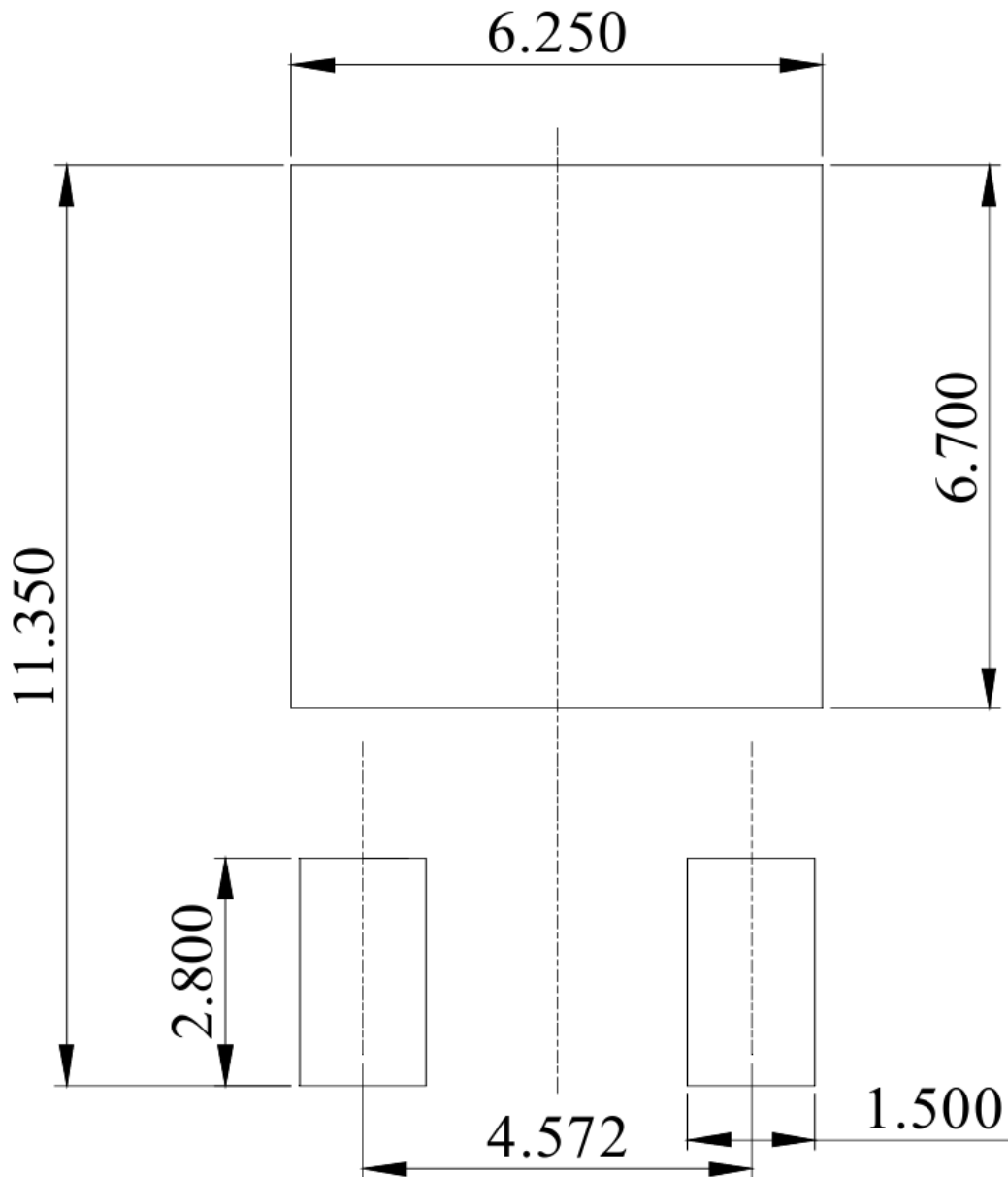
Package Outline Type-B



DIM.	MILLIMETER		
	MIN.	NOM.	MAX.
A	2.10	2.30	2.40
A1	0	--	0.13
b	0.66	0.76	0.86
b3	5.21	5.38	5.55
c	0.40	0.50	0.60
c1	0.44	0.50	0.58
D	5.90	6.10	6.30
D1	5.30REF		
E	6.40	6.60	6.80
E1	4.63	-	-
e	2.29 BSC		
H	9.50	10.00	10.70
L	1.09	--	1.21
L2	1.35	--	1.65
V1	7° REF		
V2	0°	--	6°



Recommended Soldering Footprint



DIMENSIONS:MILLIMETERS

Ordering information

Order Code	Package	V _{DS} (V)	I _D (A)	R _{DS(ON)} (m Ω)	
QND160N03C	TO-252	30	160	V _{GS} =10	< 3.5
				V _{GS} =4.5	< 4.5